

Day : Monday
Date: 7/27/2009

Time: 09:21:11

 PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = MASUDA

First Name = TAKATO

Application#	Patent#	PG Pub#	Status	Date Filed	Title	Examiner Name
07862619	Not Issued		166	04/01/1992	HIGH TEMPERATURE SUPERCONDUCTING COIL AND METHOD OF MANUFACTURING THEREOF	BARRERA,RAMC
08385571	5512867		150	02/08/1995	HIGH TEMPERATURE SUPERCONDUCTING COIL AND METHOD OF MANUFACTURING THEREOF	BARRERA,RAMC
09758261	6552260	20010054509	150	01/12/2001	SUPERCONDUCTING CABLE AND METHOD OF ANALYZING THE SAME	PALADINI,ALBE
10045027	6718618	20020148101	150	01/15/2002	METHOD OF MANUFACTURING SUPERCONDUCTING CABLE	ARBES,CARL
10498059	7296419	20050067174	150	06/09/2004	COOLING METHOD OF SUPERCONDUCTING CABLE LINE	ALI,MOHAMMAI
10549578	Not Issued	20060180328	71	09/19/2005	Super-conductive cable operation method and super-conductive cable system	ALI,MOHAMMAI
10591000	Not Issued	20070169957	41	08/29/2006	Splice structure of superconducting cable	NORRIS,JEREMY

10591949	Not Issued	20070191231	30	09/08/2006	Terminal structure of superconducting cable	VIJAYAKUMAR,)
10840232	7067739	20040259408	150	05/07/2004	JOINT STRUCTURE OF SUPERCONDUCTING CABLE AND INSULATING SPACER FOR CONNECTING SUPERCONDUCTING CABLE	MAYO III,WILLIA
10840334	7439448	20040256142	150	05/07/2004	PHASE SPLIT STRUCTURE OF MULTIPHASE SUPERCONDUCTING CABLE	NORRIS,JEREMY
10845069	7168744	20040256855	150	05/14/2004	FASTENING STRUCTURE FOR USE AT LOW TEMPERATURE	HEWITT,JAMES
10862340	7148423	20040256144	150	06/08/2004	PHASE SPLIT STRUCTURE OF MULTIPHASE SUPERCONDUCTING CABLE	SEMENENKO,YU
11014135	7265297	20050217878	150	12/17/2004	MULTIPHASE SUPERCONDUCTING CABLE CONNECTION STRUCTURE AND MULTIPHASE SUPERCONDUCTING CABLE LINE	SEMENENKO,YU
11578527	Not Issued	20070234745	61	10/13/2006	Circulation Cooling System of Cryogenic Cable	COMINGS,DANIE
11447130	Not Issued	20070004177	161	06/06/2006	Wafer processing method	TRAN,TONY
11529137	Not Issued	20070077731	93	09/28/2006	PROCESSING METHOD OF WAFER	NHU,DAVID
11604210	7439162	20070123002	150	11/27/2006	METHOD OF DIVIDING WAFER INTO INDIVIDUAL DEVICES AFTER FORMING A RECESSED PORTION	HUYNH,ANDY

					OF THE WAFER AND MAKING THICKNESS OF WAFER UNIFORM	
11641517	7278903	20070141955	150	12/19/2006	PROCESSING METHOD FOR WAFER AND PROCESSING APPARATUS THEREFOR	ACKUN,JACOB
11715999	Not Issued	20070218593	93	03/09/2007	METHOD FOR PRODUCING SEMICONDUCTOR PACKAGE	ZARNEKE,DAVII
11728931	Not Issued	20070231929	61	03/27/2007	Processing method for wafer	MUSTAPHA,ABD
11728936	Not Issued	20070227655	25	03/27/2007	Processing method for wafer and processing apparatus therefor	,
11787627	Not Issued	20070249146	30	04/17/2007	Protective tape applying method	SINGAL,ANKUSH
12243483	Not Issued	20090098808	30	10/01/2008	GRINDING METHOD FOR WAFER	MORGAN,EILEEN
12349770	Not Issued	20090186562	20	01/07/2009	METHOD OF GRINDING WAFER	,
12408469	Not Issued	0	30	03/20/2009	GRINDING METHOD FOR WAFER HAVING CRYSTAL ORIENTATION	HAIL,JOSEPH

Inventor Search Completed: No Records to Display.

Search Another: Inventor	Last Name	First Name
	<input type="text" value="masuda"/>	<input type="text" value="takato"/>
	<input type="button" value="Search"/>	

To go back use Back button on your browser toolbar.

Back to [PALM ASSIGNMENT](#) | [OASIS](#) | [Home page](#)